

Appl. No. 10/709,663
Amtd. dated November 23, 2004
Reply to Office action of August 30, 2004

AMENDMENTS TO THE CLAIMS

1. (currently amended) A method for manufacturing a light emitting diode having a transparent substrate, the method comprising:
 - 5 forming a semiconductor multilayer on a first substrate producing a first multilayer structure;
 - 10 forming ~~an-a conductive~~ amorphous interface layer on a second substrate, the second substrate being transparent in nature, producing a second multilayer structure;
 - 15 bonding the first multilayer structure to the second multilayer structure, producing a third multilayer structure; and
 - 20 removing the first substrate from the third multilayer structure.
- 15 2. (original) The method of claim 1 further comprising a step of forming a transparent conductive layer on the third multilayer structure after removing the first substrate.
3. (currently amended) The method of claim 1, wherein the amorphous interface layer is made of at least one selected from a group ~~comprising~~ consisting of indium tin oxide, indium cadmium oxide, indium antimony tin oxide, and transparent-conductive adhesive agent.
- 25 4. (currently amended) A method for manufacturing a light emitting diode, comprising:
 - forming a semiconductor multilayer on a first substrate producing a first multilayer structure;
 - 25 forming ~~an-a conductive~~ amorphous interface layer on a second substrate, the second substrate being transparent in nature, producing a second multilayer

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structure;

bonding the first multilayer structure to the second multilayer structure, producing
a third multilayer structure; and

5 removing the first substrate from the third multilayer structure.

5. (original) The method of claim 4 further comprising a step of forming a transparent conductive layer on the third multilayer structure after removing the first substrate.

10 6. (currently amended) The method of claim 4, wherein the amorphous interface layer is made of at least one selected from a group comprising consisting of indium tin oxide, cadmium tin oxide, antimony tin oxide, and transparent conductive-adhesive agent.